

Glass Passivated Bridge Rectifiers

FEATURES

- Ideal for printed circuit board
- High case dielectric strength
- High surge current capability
- UL Recognized File # E-326243
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21 definition

MECHANICAL DATA

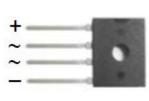
Case: D3K

Molding compound, UL flammability classification rating 94V-0 Base P/N with suffix "G" on packing code - halogen-free

Terminal: Matte tin plated leads, solderable per JESD22-B102 Meet JESD 201 class 1A whisker test

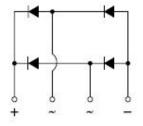
Weight: 1.24 g (approximately)

Mounting Torque: 0.8 N.M max.



D3K





MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS (T _A =25°C unless otherwise noted)					
PARAMETER	SYMBOL	UR4KB UR4KB UR4		UR4KB	
FARAINETER		60	80	100	UNIT
Maximum repetitive peak reverse voltage	V _{RRM}	600	800	1000	V
Maximum RMS voltage	V _{RMS}	420	560	700	V
Maximum DC blocking voltage	V _{DC}	600	800	1000	V
Maximum average forward current Without heat sink T_c =120°C 60Hz sine wave resistance load With heat sink T_c =138°C	I _{F(AV)}	2 4		А	
Peak forward surge current, 8.3 ms single half sine-wave superimposed on rated load	I _{FSM}	135		A	
Rating of fusing (t < 8.3ms)	l ² t	75		A ² s	
Maximum instantaneous forward voltage (Note 1) I _F = 2 A	V _F	1.0		V	
Maximum DC reverse current at rated DC blocking voltage	I _R	10		μA	
Typical thermal resistance	R _{θJC} R _{θJL} R _{θJA}	8.2 9.3 14		°C/W	
Operating junction temperature range	TJ	- 55 to +150		°C	
Storage temperature range	T _{STG}	- 55 to +150		°C	

Note 1: Pulse Test with PW=300µs,1% Duty Cycle



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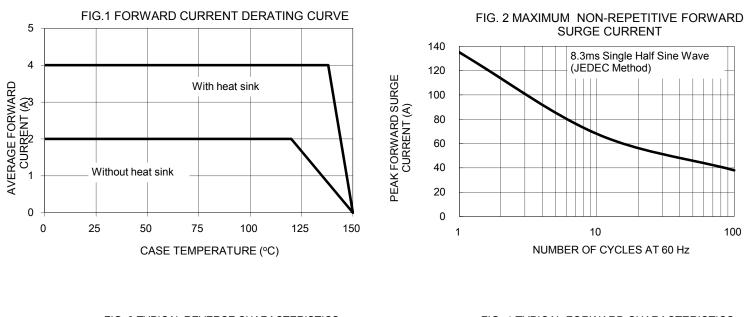
ORDERING INFORMATION					
PART NO.	PACKING CODE	GREEN COMPOUND CODE	PACKAGE	PACKING	
UR4KBx0 (Note 1)	C2	Suffix "G"	D3K	1,500 / BOX	

Note 1: "x" defines voltage from 600V (UR4KB60) to 1000V (UR4KB100)

EXAMPLE						
PREFERRED P/N	PART NO.	PACKING CODE	GREEN COMPOUND CODE	DESCRIPTION		
UR4KB60 C2	UR4KB60	C2				
UR4KB60 C2G	UR4KB60	C2	G	Green compound		

RATINGS AND CHARACTERISTICS CURVES

(TA=25 $^\circ\!\mathrm{C}$ unless otherwise noted)



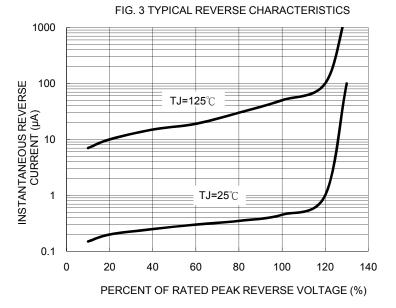
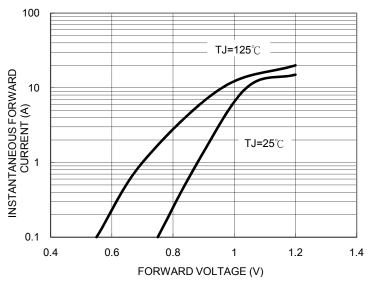
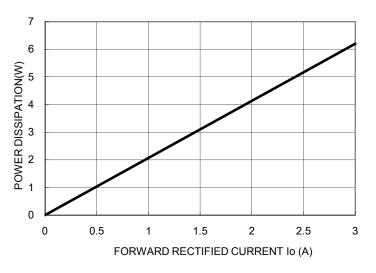


FIG. 4 TYPICAL FORWARD CHARACTERISTICS

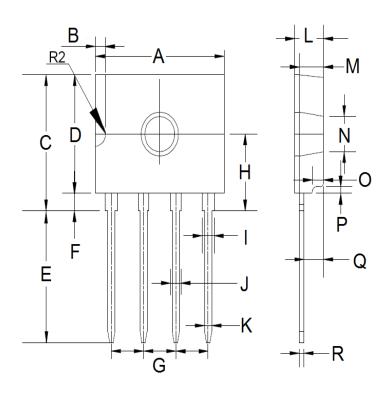








PACKAGE OUTLINE DIMENSIONS



P/N

YWW

G

F

DIM.	Unit (mm)		Unit (inch)		
DIIVI.	Min	Max	Min	Max	
А	13.50	14.10	0.531	0.555	
В	0.70	1.40	0.028	0.055	
С	11.70	12.30	0.461	0.484	
D	10.50	11.10	0.413	0.437	
E	11.70	12.30	0.461	0.484	
F	1.10	1.40	0.043	0.055	
G	3.51	4.11	0.138	0.162	
Н	6.70	7.30	0.264	0.287	
I	1.10	1.50	0.043	0.059	
J	1.05	1.25	0.041	0.049	
К	0.66	0.86	0.026	0.034	
L	2.90	3.30	0.114	0.130	
М	2.40	2.80	0.094	0.110	
N	3.10	3.40	0.122	0.134	
0	1.00	1.40	0.039	0.055	
Р	0.40	0.80	0.016	0.031	
Q	1.80	2.40	0.071	0.094	
R	0.40	0.60	0.016	0.024	

MARKING DIAGRAM



- = Specific Device Code
- = Green Compound
- = Date Code
- = Factory Code



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